

Appl. No. 10/710,522  
Reply to Office action of December 04, 2007

Amendments to the Claims:

The listing of claims will replace all prior versions and listings of claims in the application:

5

Listing of Claims:

Claim 1 (currently amended): ~~[[An]] A post-etch wet cleaning process~~ ~~extrusion-free wet cleaning process~~, comprising:

providing a wet cleaning tool;

10

preparing a wafer having a main surface comprising at least one copper wire line, exposed copper feature and a dielectric film formed on the copper metal feature and at least one opening formed in the dielectric film, wherein at least a portion of the copper wire line is exposed through the opening;

15

transferring said wafer into said wet cleaning tool in a light inhibited manner;  
and

cleaning said main surface of said wafer by contacting a cleaning solution in said light inhibited manner.

Claim 2 (currently amended): ~~The post-etch wet cleaning process~~ ~~extrusion-free wet cleaning process~~ according to claim 1 wherein said wafer is a semiconductor wafer.

20

Claim 3 (currently amended): ~~The post-etch wet cleaning process~~ ~~extrusion-free wet cleaning process~~ according to claim 1 wherein said exposed copper feature is damascened into said dielectric film.

25 Claim 4 (currently amended): ~~The post-etch wet cleaning process~~ ~~extrusion-free wet cleaning process~~ according to claim 1 wherein during said cleaning step of said main surface of said wafer in said light inhibited manner, said wafer is not exposed to light.

RECEIVED  
CENTRAL FAX CENTER

JAN 29 2008

Appl. No. 10/710,522  
Reply to Office action of December 04, 2007

Claim 5 (currently amended): The post-etch wet cleaning process ~~extrusion-free wet-~~  
~~cleaning process~~ according to claim 1 wherein said wet cleaning tool comprises a  
succession of sinks containing said cleaning solution.

5 Claim 6 (currently amended): The post-etch wet cleaning process ~~extrusion-free wet-~~  
~~cleaning process~~ according to claim 1 wherein said wet cleaning tool is a  
single-wafer cleaning tool.

Claims 7 -- 11 (canceled)